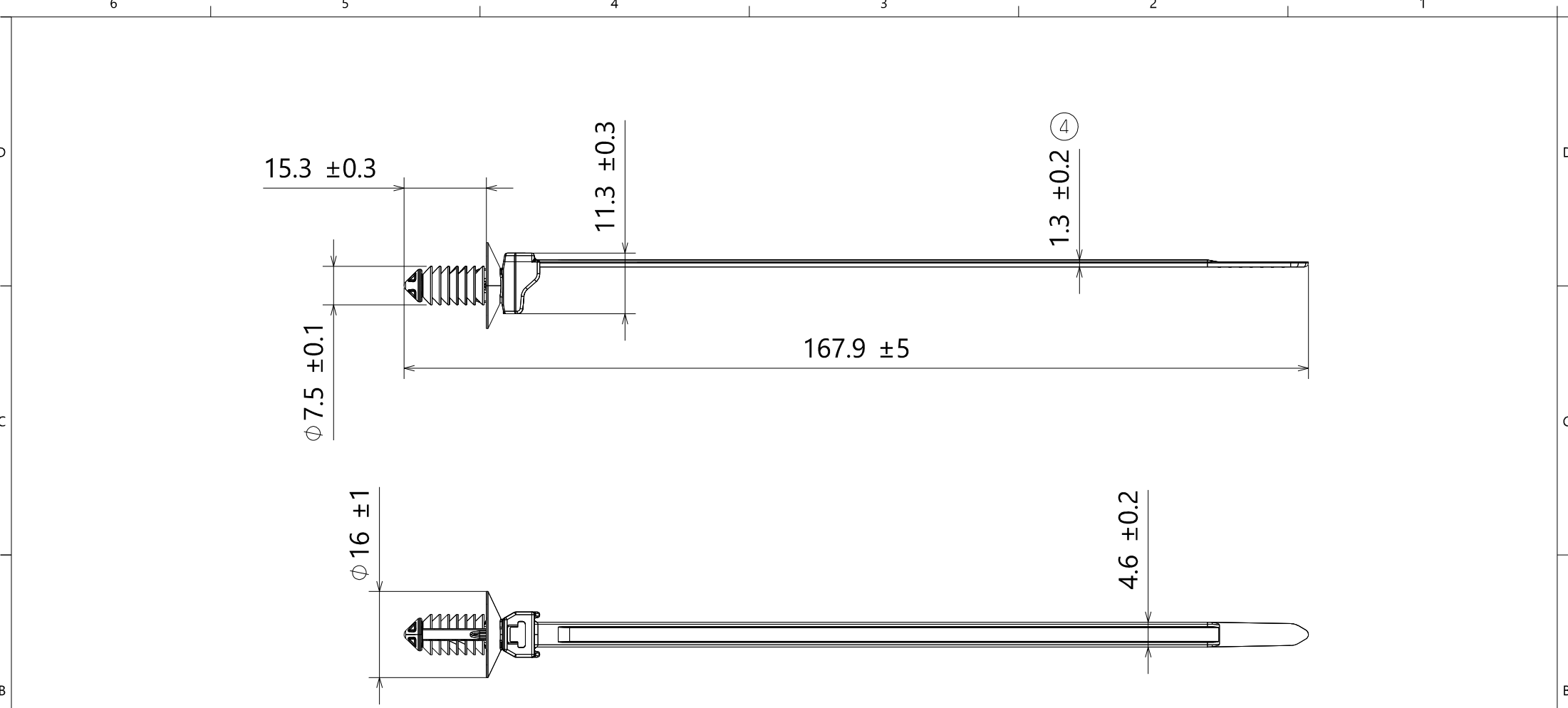
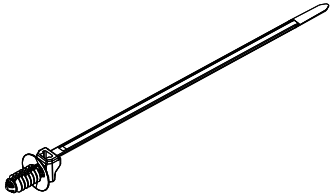
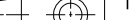




Product Type 产品型号	Hole Size 适用孔径	Bundle Dia 捆绑直径	Panel Thickness 适用板厚	Material 材料
T50SOSFT6.5LG-E4	Ø6.5±0.4mm 6.35±0.25mm HEX	1.0-35.0mm	0.6-8.25mm	PA66HIRHSB
				PA46-GY
				PA66HS-GY
				PA66HIRHS-GY



Revision Level			Revision Record			The copyright of this drawing is reserved by HellermannTyton.	Drawn		Date (YYYY/MM/DD)		Title		Scale 1:1 Global Project Number 16-1353	
Drawing	State	Part	1. Add new material PA66HIRHS-GY.				Lance.Lv	2018/11/05	Approved	Date (YYYY/MM/DD)				
05.1	Design Release			All drawing revisions are stored in CAD PDM database	Units		HellermannTyton		Drawing-No		Format A4			
Changed		Date (YYYY/MM/DD)			mm								16-1353-021-CSC	
Daniel.Guo		2024/12/11			www.HellermannTyton.com									
Approved		Date (YYYY/MM/DD)												
Robert.Zhu		2024/12/11												